

1A, 200V Ultra Fast Surface Mount Rectifier

FEATURES

- Very low profile typical height of 0.68mm
- Reduce switching and conduction loss
- Ideal for automated placement
- Ultra fast recovery times for high frequency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	1	Α	
V_{RRM}	200	V	
I _{FSM}	15	Α	
T_{JMAX}	150	°C	
Package	Micro SMA		
Configuration	Single die		









Micro SMA



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	ESH1DM	UNIT	
Marking code on the device		D3		
Repetitive peak reverse voltage	V_{RRM}	200	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	140	V	
Forward current	I _F	1	Α	
Surge peak forward current, 8.3ms single half sine wave superimposed on rated load	I _{FSM}	15	Α	
Junction temperature	TJ	-55 to +150	°C	
Storage temperature	T _{STG}	-55 to +150	°C	

1



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	40	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	92	°C/W

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	I _F = 1A, T _J = 25°C	V _F	1.25	1.50	V
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C	· I _R	-	1	μΑ
	T _J = 125°C		-	50	μA
Junction capacitance	1MHz, V _R = 4.0V	CJ	3	-	pF
Reverse recovery time	I _F = 0.5A, I _R = 1.0A I _{rr} = 0.25A	t _{rr}	-	25	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
ESH1DM	Micro SMA	12,000 / Tape & Reel	



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

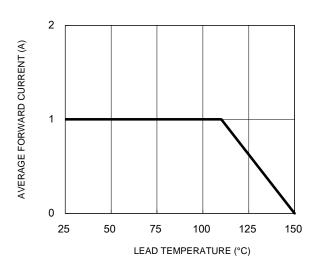


Fig.2 Maximum Non-Repetitive Forward Surge Current

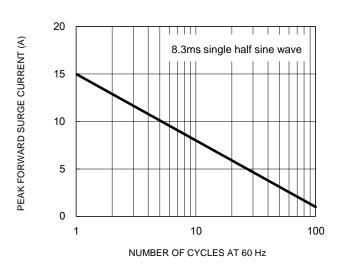
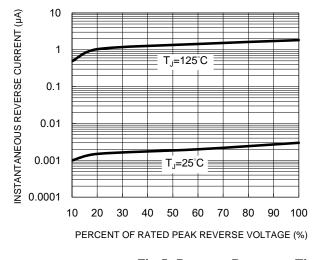


Fig.3 Typical Reverse Characteristics

Fig.4 Typical Forward Characteristics



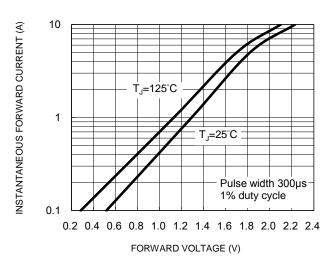
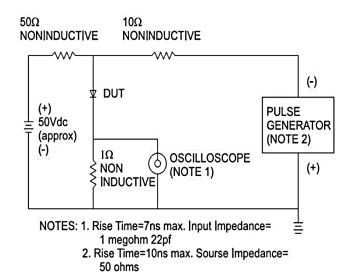
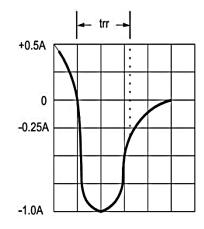


Fig.5 Reverse Recovery Time Characteristic and Test Circuit Diagram

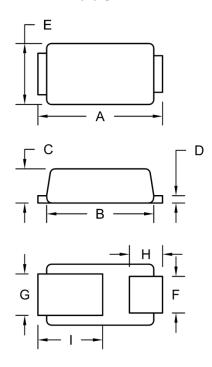






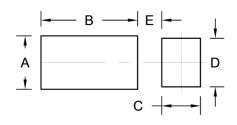
PACKAGE OUTLINE DIMENSIONS

Micro SMA



DIM.	Unit	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	2.30	2.70	0.091	0.106	
В	2.10	2.30	0.083	0.091	
С	0.63	0.73	0.025	0.029	
D	0.10	0.20	0.004	0.008	
E	1.15	1.35	0.045	0.053	
F	0.65	0.85	0.026	0.034	
G	0.75	0.95	0.030	0.037	
Н	0.55	0.75	0.022	0.030	
I	1.10	1.50	0.043	0.059	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



P/N = Marking Code YW = Data Code



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